

## AMENDMENTS TO THE CLAIMS

Cancel claims 3, 8-10 and 15-18 without prejudice

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (currently amended) A method comprising:

providing a circuit board having a plurality of holes formed therethrough; and

mounting a spring to an underside of the circuit board, the mounted spring having a plurality of holes each aligned with a respective one of the holes in the circuit board;

wherein the spring includes a plurality of bosses, each having one of the holes of the spring formed therethrough, and the method further comprising:

sandwiching each of the bosses of the spring between a respective chassis standoff and a respective heat sink standoff;

wherein said circuit board holes are shaped and sized so that said circuit board is not sandwiched between said chassis standoffs and said heat sink standoffs.

2. (original) The method of claim 1, wherein the spring includes at least one spring finger to apply a load to the underside of the circuit board.

3. (canceled)

4. (currently amended) The method of claim 3 1, further comprising simultaneously inserting a fastener through one of the holes of the circuit board and through a corresponding hole of the spring.

5. (original) The method of claim 2, wherein the plurality of holes of the spring includes four holes.

6. (original) The method of claim 5, wherein the plurality of holes of the circuit board includes four holes located to define a rectangle.

7. (original) The method of claim 1, wherein the mounting of the spring to the underside of the circuit board includes inserting each of a plurality of board attach fingers of the spring through a respective one of the holes of the circuit board.

8-10. (canceled)

11. (currently amended) ~~The spring of claim 10;~~

A spring comprising:

a perimeter section including a plurality of sides around an open space;

a first spring finger extending inwardly and upwardly in an inclined fashion from a first one of the sides;

a second spring finger extending inwardly and upwardly in an inclined fashion from a second one of the sides that is opposite to the first one of the sides;

four board attach fingers each extending substantially vertically upwardly from the perimeter section, a first one of the board attach fingers located at a first end of the first one of the sides, a second one of the board attach fingers located at a second end of the first one of the sides, a third one of the board attach fingers located at a first end of the second one of the sides, and a fourth one of the board attach fingers located at a second end of the second one of the sides; and

four bosses formed in the perimeter section, each of the bosses located so as to have a respective one of the board attach fingers extending upwardly therefrom;

wherein the perimeter section is substantially octagonal, and includes a pair of long sides that are positioned opposite to each other and that are longer than the sides from which the first and second spring fingers extend, the perimeter section further including four short sides that are shorter than the sides from which the first and second spring fingers extend, each of the short sides joining an end of one of the long sides to an end of one of the sides from which the first and second spring fingers extend;

said long sides, said short sides and said sides from which the first and second spring fingers extend together forming a closed octagonal loop.

12. (currently amended) The spring of claim 8 11, being formed of stainless steel.

13. (currently amended) The spring of claim 8 11, being formed as a single unitary piece of material.

14. (currently amended) The spring of claim 8 11, further comprising a pair of tape segments, each mounted on an upper surface of a respective one of the first and second spring fingers.

15-18. (canceled)

19. (currently amended) A system comprising:

a chassis;

a plurality of chassis standoffs mounted on the chassis;

a heat sink having a plurality of heat sink standoffs mounted on a lower side thereof;

a spring including a plurality of bosses each sandwiched between a respective one of the chassis standoffs and a respective one of the heat sink standoffs; and

a circuit board mounted in the chassis with the spring below the circuit board and the heat sink above the circuit board, the heat sink positioned to conduct heat from an integrated circuit (IC) package mounted on an upper side of the circuit board, the circuit board having a respective hole formed therein at a respective location of each of the heat sink standoffs;

the spring including at least one spring finger to apply a load to an underside of the circuit board at a locus of the IC package;

wherein said circuit board holes are shaped and sized so that said circuit board is not sandwiched between said chassis standoffs and said heat sink standoffs.

20. (original) The system of claim 19, wherein the spring includes two spring fingers in contact with the underside of the circuit board.

21. (original) The system of claim 20, further comprising four fasteners each extending downwardly through a respective one of the heat sink standoffs, through a respective hole in the circuit board, through a respective hole in the spring, and into a respective one of the chassis standoffs.